

SMD POWER COIL-JNR 6028H



FEATURES

- 1. This specification applies Low Profile Power Inductors.
- 2. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
 3. Operating temperature :-40~+125°C (Including self temperature rise)

PRODUCT IDENTIFICATION



Inductance

DIMENSIONS (mm)



Part No	Size (mm)				
Fart NO.	Α	В	С	D	Е
JNR 6028H	6.0 ± 0.2	6.0 ± 0.2	2.6 ± 0.2	1.6 ± 0.3	5.8 ± 0.3

* Dimensions are not including the termination.

For maximum overall dimensions with termination, add 0.1mm.

Recommended PC Board Pattern



Note:

1.PCB layout is referred to standard IPC-7351B

- 2. The above PCB layout reference only.
- 3. Recommend solder paste thickness at 0.15mm and above.

SERIES LIST

		L	Tol.	RDC	Isat	Irms
No.	Part No.			(m Ω)	(A)	(A)
		(μH)		±20%		
1	JNR 6028H-1R0N	1.0	±30%	10	5.75	5.20
2	JNR 6028H-1R5N	1.5	±30%	14	5.30	4.95
3	JNR 6028H-2R2M	2.2	±20%	18	5.00	4.50
4	JNR 6028H-3R3M	3.3	±20%	24	4.30	3.60
5	JNR 6028H-4R7M	4.7	±20%	30	3.20	3.10
6	JNR 6028H-6R8M	6.8	±20%	47	2.85	2.50
7	JNR 6028H-100M	10	±20%	65	2.10	2.00
8	JNR 6028H-150M	15	±20%	98	2.00	1.80
9	JNR 6028H-220M	22	±20%	138	1.60	1.50
10	JNR 6028H-330M	33	±20%	200	1.40	1.30
11	JNR 6028H-470M	47	±20%	280	1.15	1.06
12	JNR 6028H-680M	68	±20%	420	1.00	0.81
13	JNR 6028H-101M	100	±20%	605	0.80	0.72

Note:

1. Test Frequency : 100KHz /1V

2. All test data referenced to $25^\circ\!\mathrm{C}$ ambient

3. Isat : Saturation Current (Isat) will cause L0 to drop approximately 30%.

4. Irms : Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of $40^\circ\!\mathrm{C}$

5. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

6. Special inquiries besides the above common used types can be met on your requirement.

7. Rated DC current: The lower value of Irms and Isat.

Materials



No.	Description	Specification	
а	Core	Ferrite Core	
b	Wire	Enameled Copper Wire	
С	Glue	Epoxy with magnetic powder	
d	Terminal	Ag/Ni/Sn+ Sn Solder	
е	Ink	Halogen-free ketone	

TYPICAL PERFORMANCE CURVES

















JNR 6028H-3R3

























Appearance criterion

1 . Core chipping

The appearance standard of the chipping size on top side, and bottom side ferrite core is listed below. Chip off is generated during molding and manufacturing process.

Chip off acceptance limits subjected to the product size.

Our current Defect limit is based on the IPC-A-610.

Some chip off does not impact the product function, see the IPC standard 1 & 2.



L	\leq 50 % of the length
W	\leq 25 % of the width

Defects usually occur at the corners and edges of the product, There will be a slight defect black and rough, but not exposed copper, and does not affect the product performance and reliability.

2 · Void appearance tolerance Limit

Size of voids occurring to coating resin is specified below.



Exposed wire tolerance limit of coating resin part on product side. Size of exposed wire occurring to coating resin is specified below.

- 1. Width direction (dimension a) : Acceptable when $a \leq w/2$.
- 2. Length direction (dimension b) : Dimension b is not specified.
- 3. The total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, and is acceptable.

3 . External appearance criterion for exposed wire

Exposed winding wire at the secondary side is regarded as qualified product.



4、 Electrode appearance criterion for exposed wire







Size	Reel
JNR 6028H	1500

• Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions (referenced ANSI/EIA-481-D-2008 of 4.11 standard).

Tearing Speed	Room Temp.	Room Humidity	Room atm
mm	(°C)	(%)	(hPa)
300±10%	5~35	45~85	860~1060

Application Notice

· Storage Conditions(component level)

To maintain the solderability of terminal electrodes:

- 1. Products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
- 2. Temperature and humidity conditions: Less than $40^\circ\!\mathrm{C}$ and 60% RH.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.

Transportation

- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.